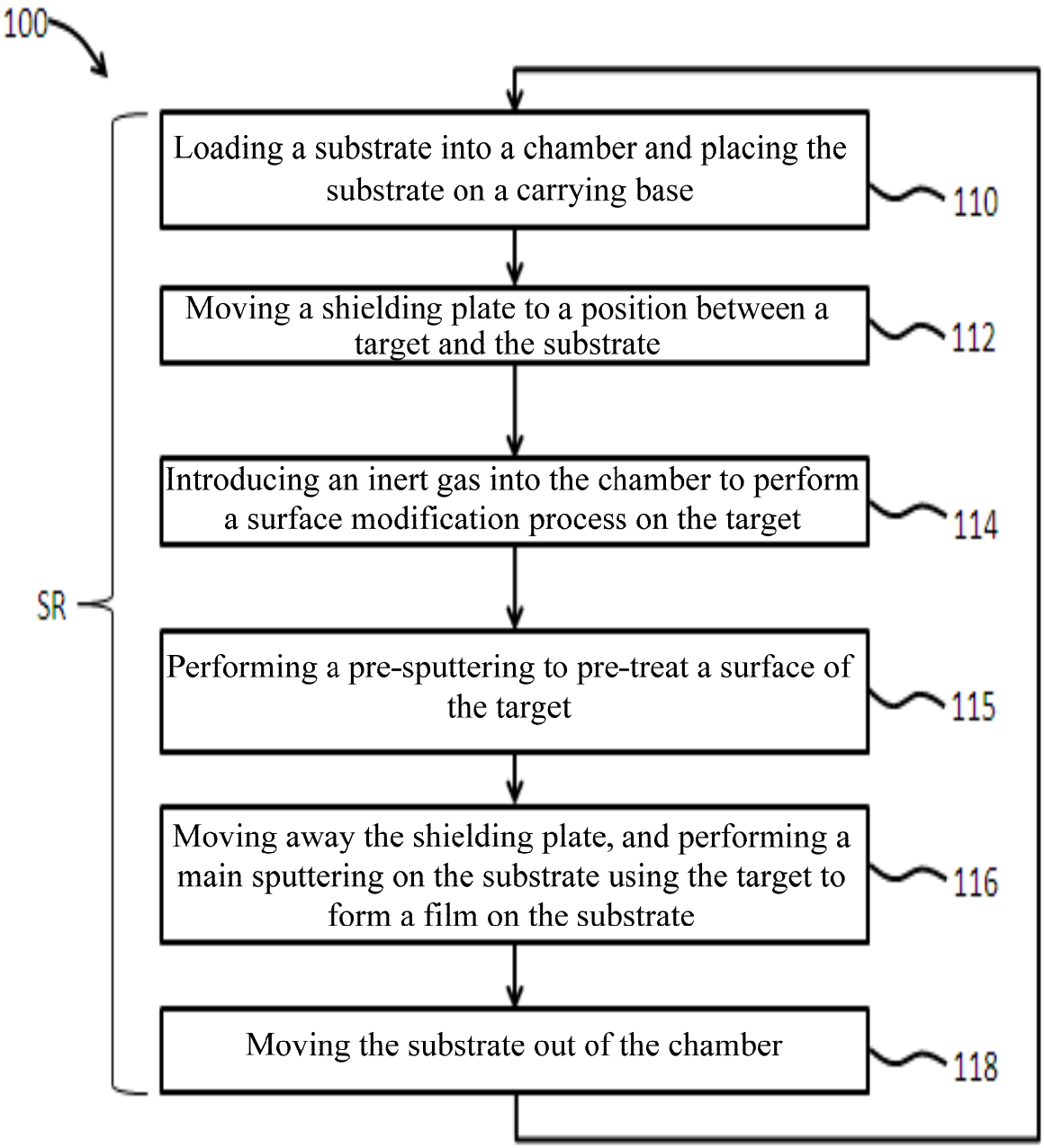

100
Loading a substrate into a chamber and placing the substrate on a carrying base
110
Moving a shielding plate to a position between a target and the substrate
112
Introducing an inert gas into the chamber to perform a surface modification process on the target
114
SR
Performing a pre-sputtering to pre-treat a surface of the target
115
Moving away the shielding plate, and performing a main sputtering on the substrate using the target to form a film on the substrate
116
Moving the substrate out of the chamber
118

FIG. 1

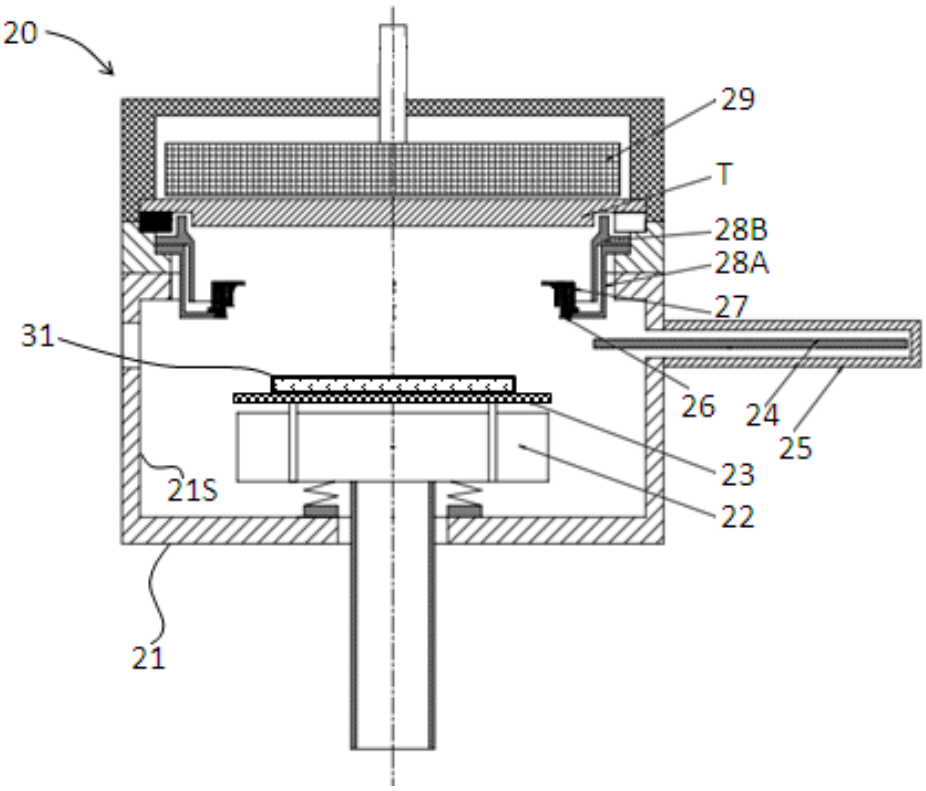
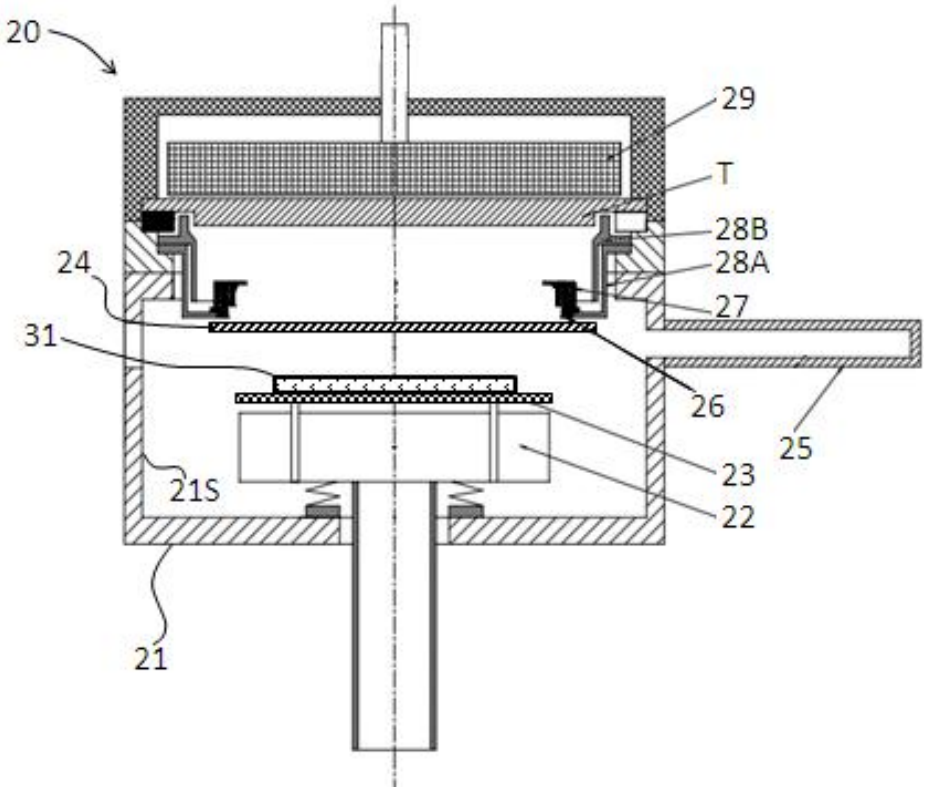

20
29
T
28B
28A
27
31
26
24
25
23
22
21S
21

FIG. 2A


20
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28B
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28A
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21S
21

FIG. 2B

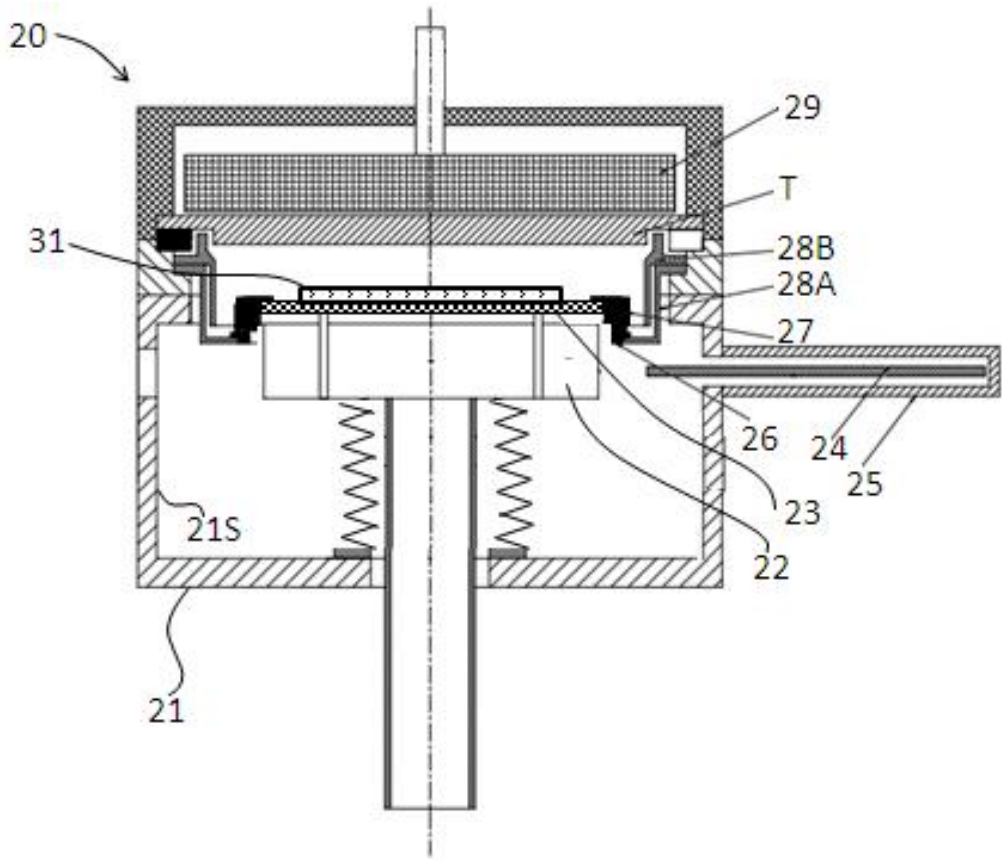

FIG. 2C

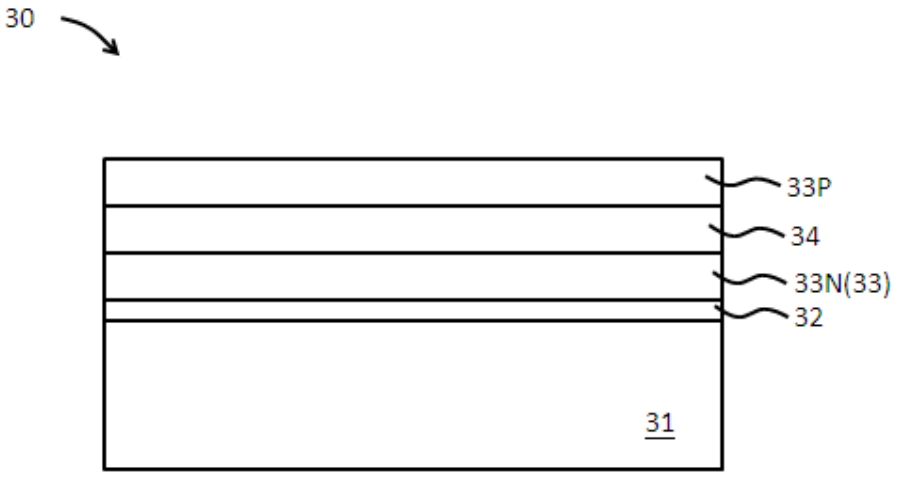

FIG. 3